

Agenda

2011 iNEMI Roadmap North American TWG Kickoff Meeting

Agilent Technologies

5301 Stevens Creek Blvd, Building 5 – Aristotle Room

Santa Clara, California

Tuesday, February 23, 2010

Time	Subject	Presenter
7:30 a.m.	Continental Breakfast (Welcome)	Mike Davisson, Agilent
8:00 a.m.	“Designing for Mfg. Success”	Mark Pierpoint, Agilent Technologies
8:30 a.m.	Welcome/Agenda Overview	Chuck Richardson, iNEMI
8:45a.m. – 12:00 p.m.	Product Emulator Group Presentations	
8:45 a.m.	Portable/Consumer Products	Shahrokh Shahidzadeh, Intel
9:15 a.m.	Office/Large Business Systems	David Lober, Intel
9:45 a.m.	Automotive	Jim Spall, Delphi
10:15 – 10:30 a.m.	Break	
10:30 a.m.	Aerospace/Defense	William Murphy, Lockheed Martin
11:00 a.m.	Medical	Anthony Primavera, Micro Systems Engineering
11:30 a.m.	Netcom Products	John Duffy, Cisco
12:00 p.m.	Summary	Chuck Richardson, Bob Pfahl, iNEMI
12:15 p.m.	Lunch	
1:15 p.m.	Introduction to Breakout Sessions	Chuck Richardson, iNEMI
1:30-5:00 p.m.	Breakout Sessions (follow TWG signs)	
5:00 p.m.	Summary	Chuck Richardson, Bob Pfahl iNEMI
5:15 p.m.	Close	

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Wednesday, February 24, 2010

Time	Subject	Presenter
7:30 a.m.	Continental Breakfast	
8:00 a.m.	Introduction to Reports	Chuck Richardson, iNEMI
8:15 a.m. – 12:00 p.m.	Technical Working Group Reports:	
	Design Technologies:	
8:15 a.m.	Environmentally Conscious Electronics	Jackie Adams, IBM
8:25 a.m.	Modeling, Simulation & Design Tools	Yishao Lai, ASE
8:35 a.m.	Thermal Management	Ravi Prasher, Intel
	Manufacturing Technologies:	
8:45 a.m.	Board Assembly	Paul Wang, Mitac
8:55 a.m.	Test, Inspection & Measurement	Mike Reagin, Delphi
9:05 a.m.	Final Assembly	John Allen, Celestica
	Component Subsystem Technologies:	
9:15 a.m.	Passive Components	TBD
9:25 a.m.	RF Components & Subsystems	Ken Harvey, Peak Consulting
9:35 a.m.	Packaging & Component Substrates	Bill Bottoms, 3MTS
9:45 a.m.	Semiconductor Technology	Alan Allan, Intel
9:55 a.m.	Interconnect PCB (Organic)	Jack Fisher, IPC
10:05 a.m.	Break	
	Business Processes / Technologies:	
10:20 a.m.	Information Management	Jeff Pettinato, Intel
	Component Subsystem Technologies:	
10:30 a.m.	Electronic Connectors	John MacWilliams, Bishop
10:40 a.m.	Energy Storage & Conversion Systems	Nadim Maluf, QNovo
10:50 a.m.	Optoelectronics	Dick Otte, Promex
11:00 a.m.	MEMS/Sensors	John McKillop, Tekton LLC
11:10 a.m.	Large Area, Flexible Electronics	Dan Gamota, Printovate
11:20 a.m.	Interconnect Substrates (Ceramic)	Howard Imhof, Metalor
11:30 a.m.	Solid State Illumination	Marc Chason, Consultant
11:40 a.m.	Photovoltaics	Jim Handy, Objective Analysis
11:50 a.m.	Mass Data Storage	Roger Hoyt, Consultant
12:00 p.m.	Summary/Close/Lunch/Museum Tour	Chuck Richardson, Bob Pfahl, iNEMI